

IN THE SPECIFICATION:

Please replace the paragraph beginning at page 13, line 14, with the following rewritten paragraph:

Discussion turns next to FIGs. 11-13. More specifically, discussions with respect to FIGs. 11-13 would substantially parallel the discussions with respect to FIGs. 9 and 10 and, accordingly, redundancy is omitted for the sake of brevity. The differences between FIGs. 11-13 versus FIGs. 9 and 10 are that the thinner coating 550N of FIG. 5B is illustrated/used together with an additional adhesive layer 1250 (FIG. 12 view 1200) for use in the flip chip assembly process. The adhesive layer 1250 can be made of any suitable material, e.g., may be made of the same material as the coating 550, 550', such as a thermoplastic or thermoset polymer. As advantages, the adhesive coating 1250 is used to compensate for the fact that the planarized/pre-backfill coating 550N does not completely cover the bumps 130, and additional under-fill material is needed to fill in areas between the flip chip lands 970 and/or the remaining height of the bumps 130. The adhesive coating 1250 thus effectively serves as a secondary under-fill layer. The final result is the alternative very thin die flip chip assembly 1300, as illustrated in FIG. 13.